

Product Summary

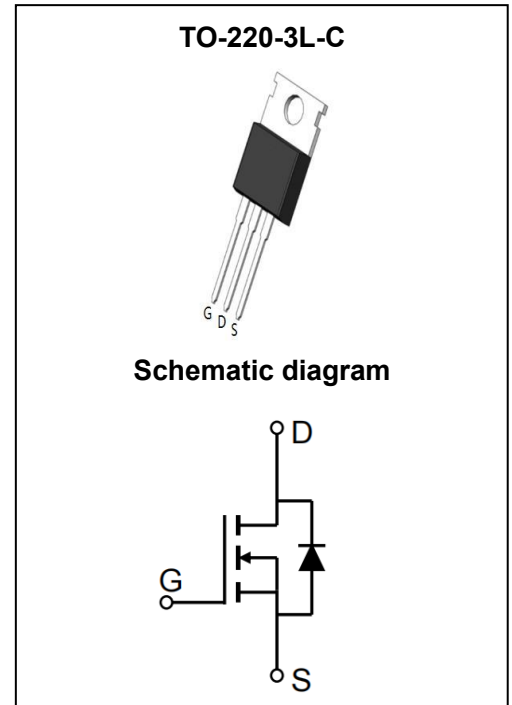
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
250V	16.6mΩ@10V	93A

Feature

- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Split Gate Trench Technology
- 100% UIS TESTED
- 100% Rg TESTED

Application

- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit
- Power Tools
- UPS
- Motor Control



Package Marking and Ordering Information

Part Number	Package	Marking	Packing	Tube	Qty
GPT166N25NTB	TO-220-3L-C	T166N25N	Tube	50pcs	5000pcs

ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	250	V
Gate - Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	$T_C = 25^{\circ}C$	93
		$T_C = 100^{\circ}C$	66
Pulsed Drain Current	I_{DM}	290	A
Single Pulsed Avalanche Energy ¹	E_{AS}	180	mJ
Power Dissipation	P_D	429	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	60	$^{\circ}C/W$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.35	$^{\circ}C/W$
Operating Junction And Storage Temperature	T_J, T_{STG}	-55~ +175	$^{\circ}C$

MOSFET ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	250			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 200V V _{GS} = 0V	T _J = 25°C		1	μA
			T _J = 100°C		100	μA
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2	3	4	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 20A		16.6	22	mΩ
Transconductance	g _{fs}	V _{DS} =5V, I _D =20A		70		S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 100V, V _{GS} = 0V, f = 1MHz		4950		pF
Output Capacitance	C _{oss}			348		
Reverse Transfer Capacitance	C _{rss}			7		
Gate Resistance	R _G	f=1MHz		3.7		Ω
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} = 125V, I _D = 20A V _{GS} = 10V		58		nC
Gate-source Charge	Q _{gs}			18		
Gate-drain Charge	Q _{gd}			6		
Turn-on Delay Time	t _{d(on)}	V _{DD} = 125V, V _{GS} = 10V, I _D = 20A R _G = 10Ω		17		ns
Turn-on Rise Time	t _r			22		
Turn-off Delay Time	t _{d(off)}			38		
Turn-off Fall Time	t _f			11		
Source - Drain Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 20A		0.9		V
Reverse Recovery Time	t _{rr}	V _R =125V, I _F = 20A, dI/dt=100A/us		168		ns
Reverse Recovery Charge	Q _{rr}				840	

Notes:

1. L=0.4mH, TC=25°C.

Typical Characteristics

Fig 1. Typical Output Characteristics

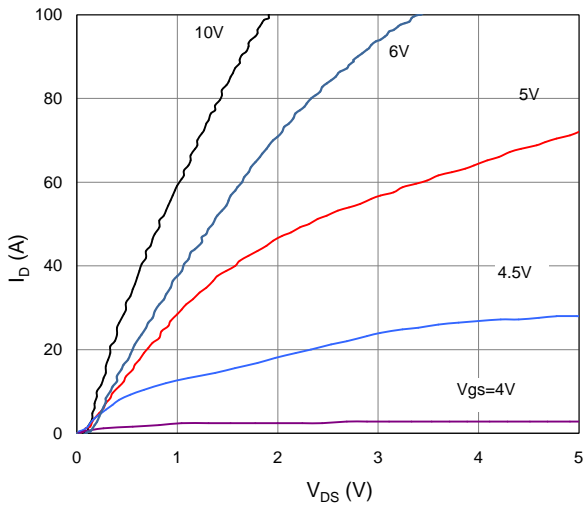


Figure 2. On-Resistance vs. Gate-Source Voltage

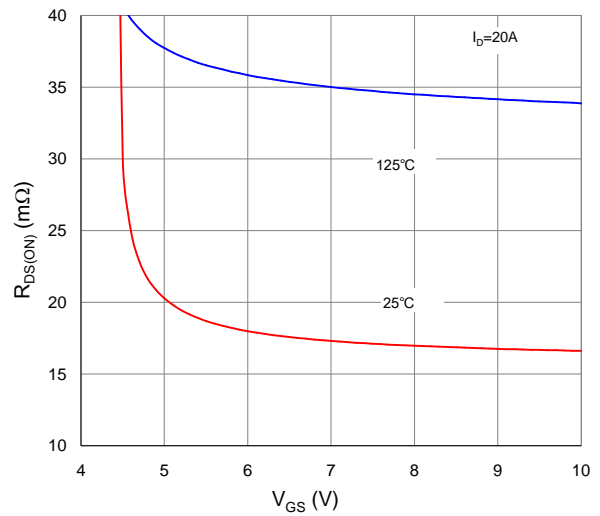


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

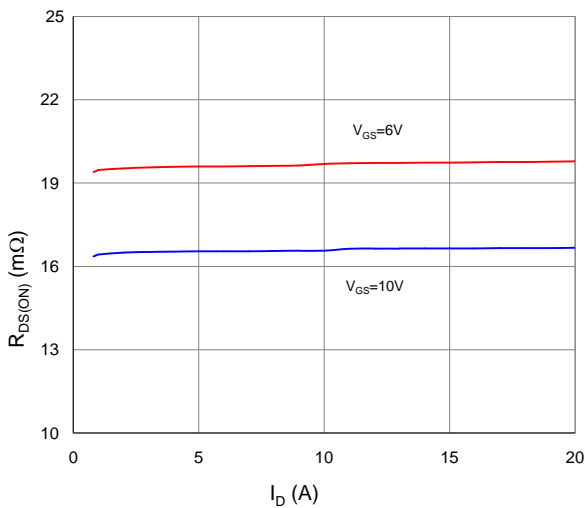


Figure 4. Normalized On-Resistance vs. Junction Temperature

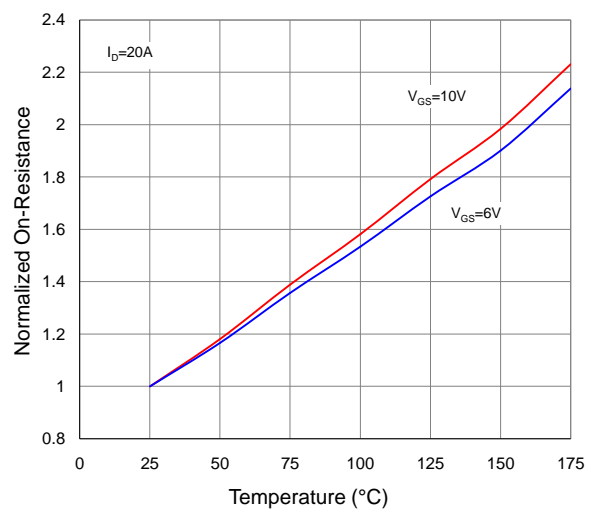


Figure 5. Typical Transfer Characteristics

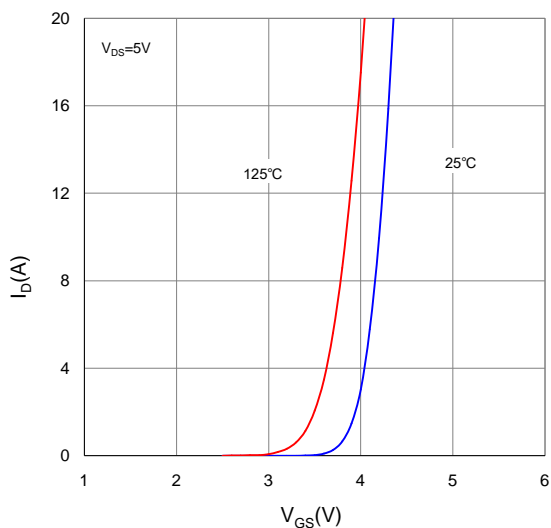
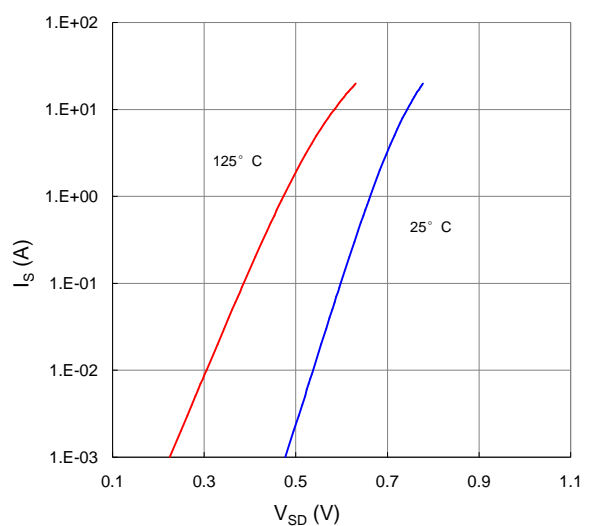


Figure 6. Typical Source-Drain Diode Forward Voltage



Typical Characteristics

Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

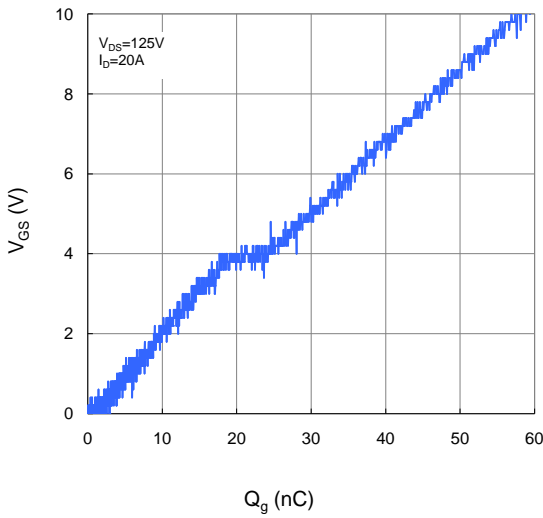


Figure 9. Maximum Safe Operating Area

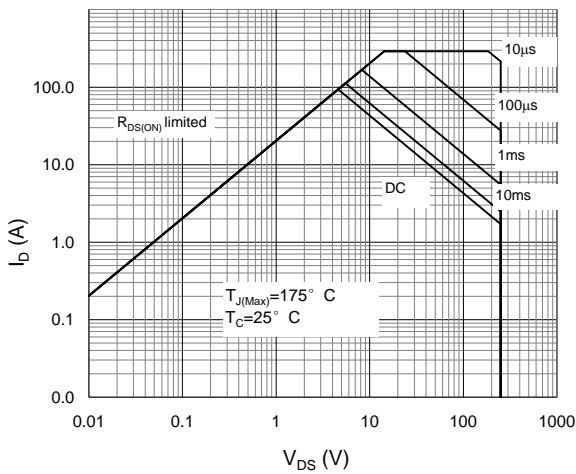


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case

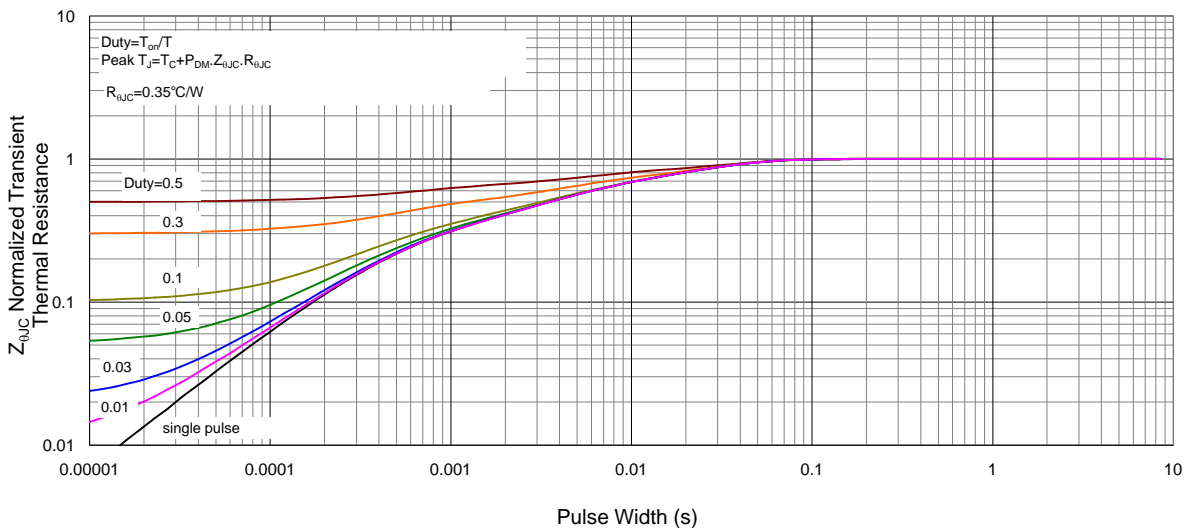


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

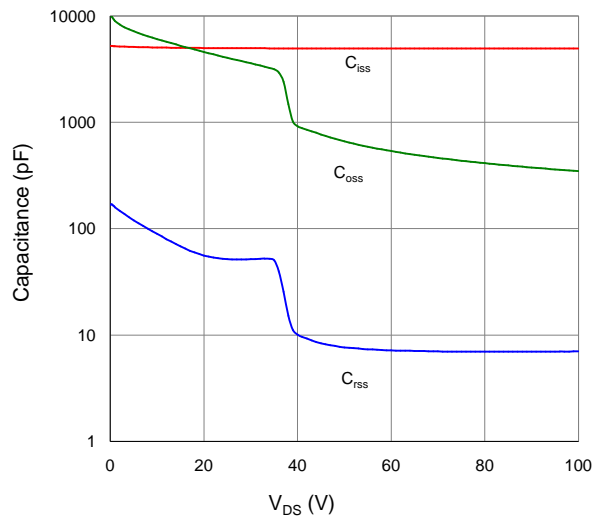
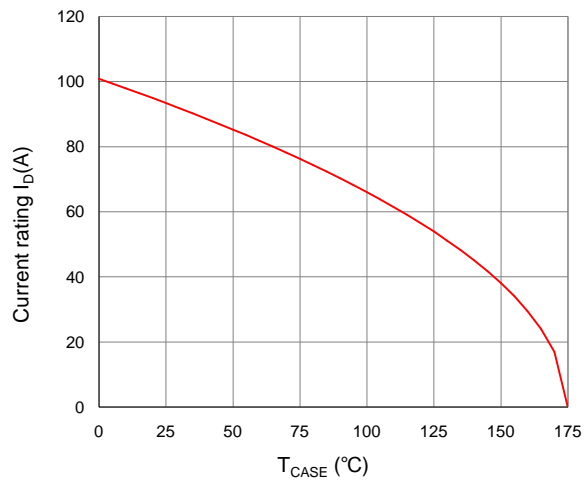
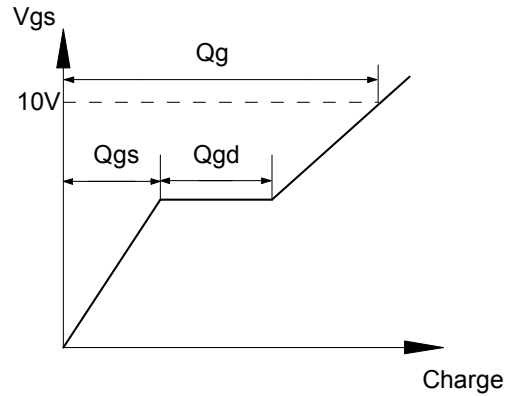
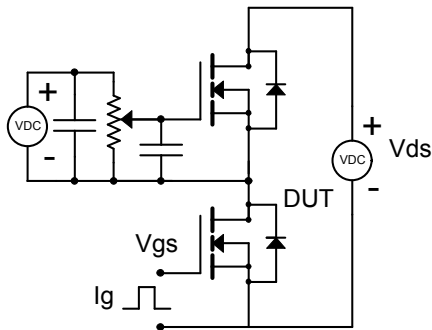


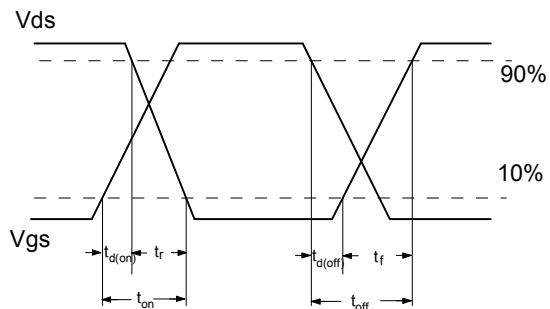
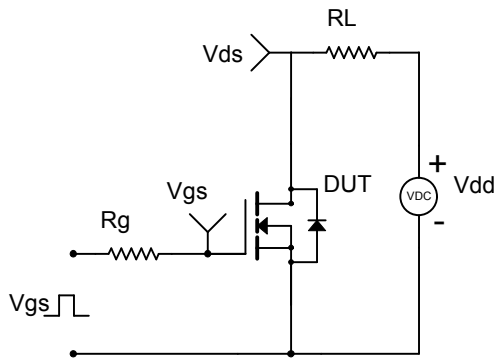
Figure 10. Maximum Drain Current vs. Case Temperature



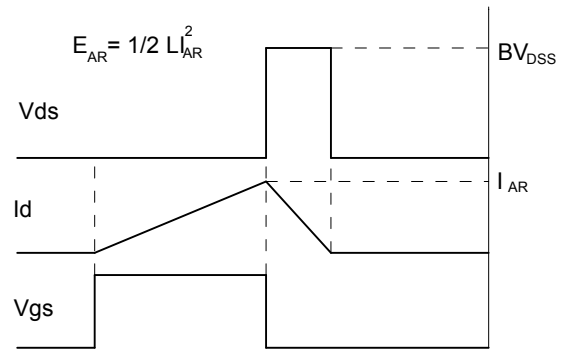
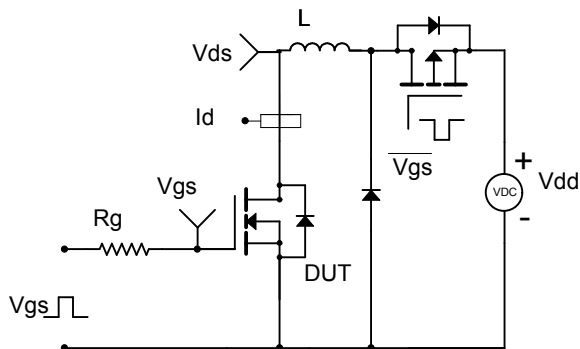
Gate Charge Test Circuit & Waveform



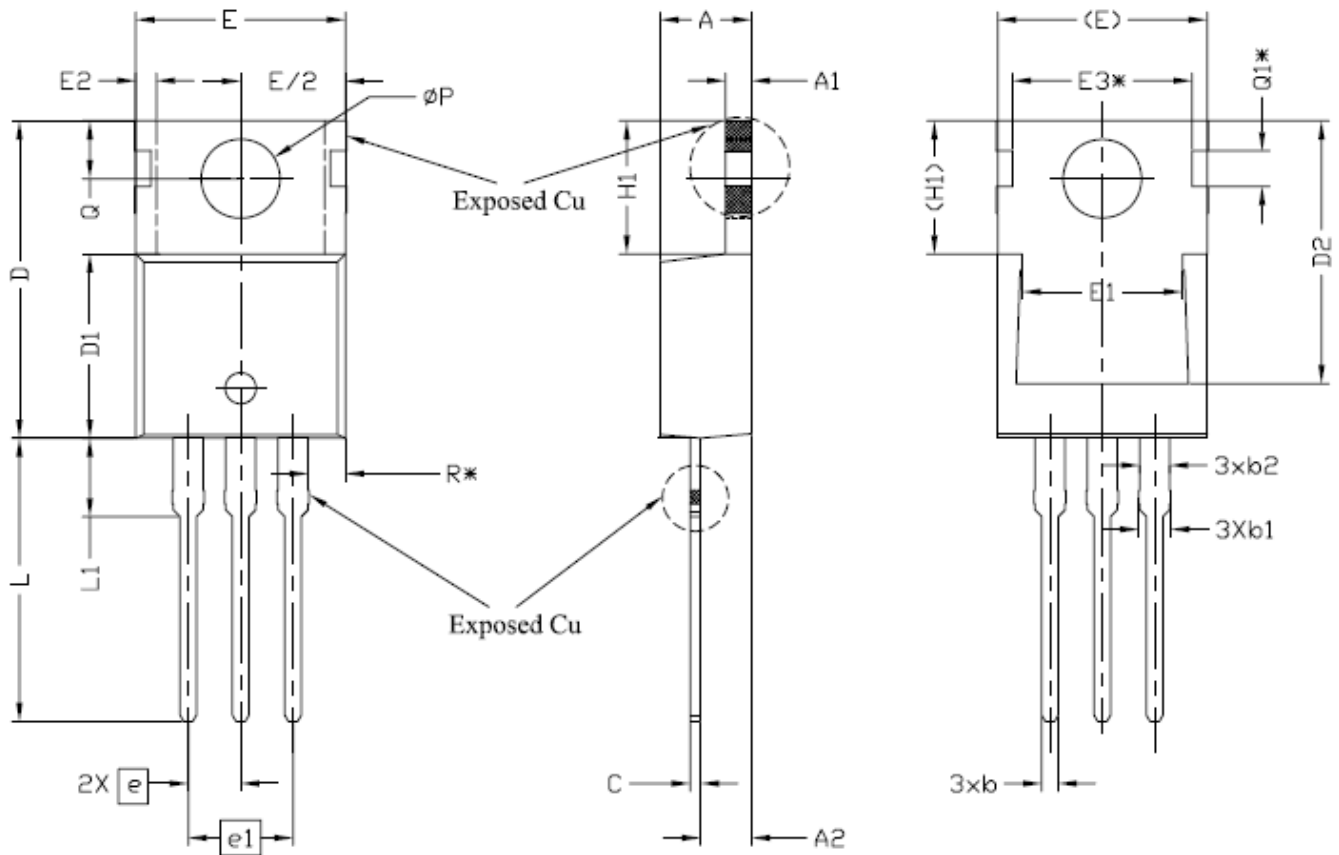
Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



TO-220-3L-C Package Information



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min.	Max.		Min.	Max.
A	4.24	4.64	E2	-	0.76
A1	1.15	1.40	E3*	8.70REF	
A2	2.30	2.70	e	2.54BSC	
b	0.7	0.9	e1	5.08BSC	
b1	1.20	1.70	H1	6.30	6.60
b2	1.20	1.70	L	13.47	13.97
c	0.40	0.60	L1	3.60	4.00
D	14.70	16.00	ϕP	3.75	3.93
D1	8.82	9.02	Q	2.60	3.00
D2	12.63	12.83	Q1*	1.73REF	
E	9.96	10.36	R*	1.82REF	
E1	6.86	8.89			

Attention:

- GreenPower Electronics reserves the right to improve product design function and reliability without notice.
- Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.
- GreenPower Electronics products belong to consumer electronics or other civilian electronic products.